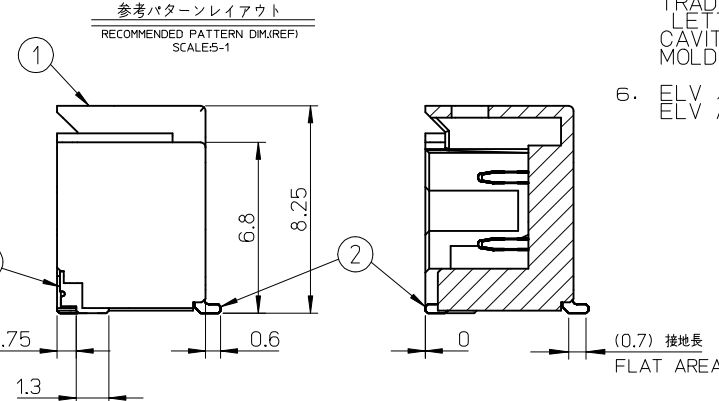
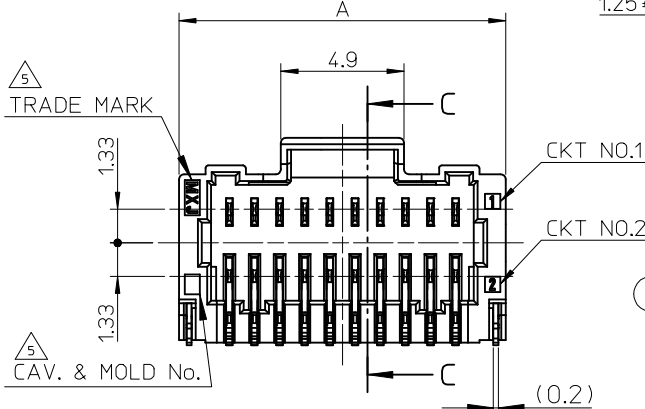
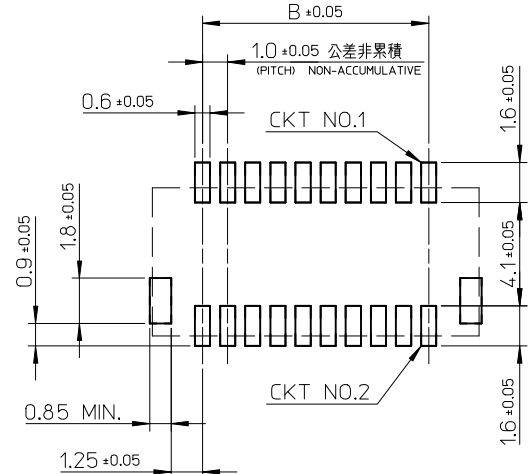
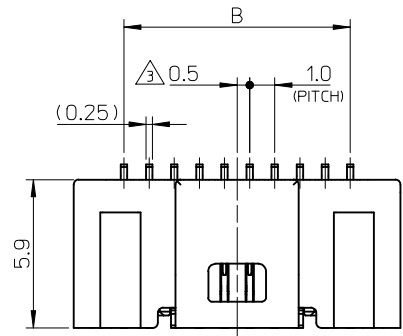


10 9 8 7 6 5 4 3 2 1



NOTES

1. 嵌合相手: 501189-****
MATE WITH: 501189-****
2. ソルダピン及びネールの平坦度は0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
3. 極数/2=偶数極の場合に適用
APPLY FOR (CIRCUIT/2=EVEN)
4. 製品番号
MATERIAL No.
501571 - **07 , 501571 - **5*
CIRCUIT SIZE CIRCUIT SIZE 色
5. トレードマーク: MXプラス1文字のアルファベットにて構成
キャビティ番号: 1桁から2桁の数字にて構成
金型番号: アルファベット1文字にて構成
TRADE MARK: FORMED BY MX AND 1 MORE
LETTER OF ALPHABET, BUT "J" MEANS JAPAN. (e.g. MXJ)
CAVITY No.: FORMED BY 1 - 2 DIGIT NUMBERS.
MOLD No.: FORMED BY 1 LETTER OF ALPHABET.
6. ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT.

SECTION C-C

24	28	501571-50**	50
19	23	501571-40**	40
14	18	501571-30**	30
9	13	501571-20**	20
B	A	EMBOSSED PACKAGE	CKT
		オーダー番号 ORDER NO.	


CONNECTOR SERIES No. 501571-****

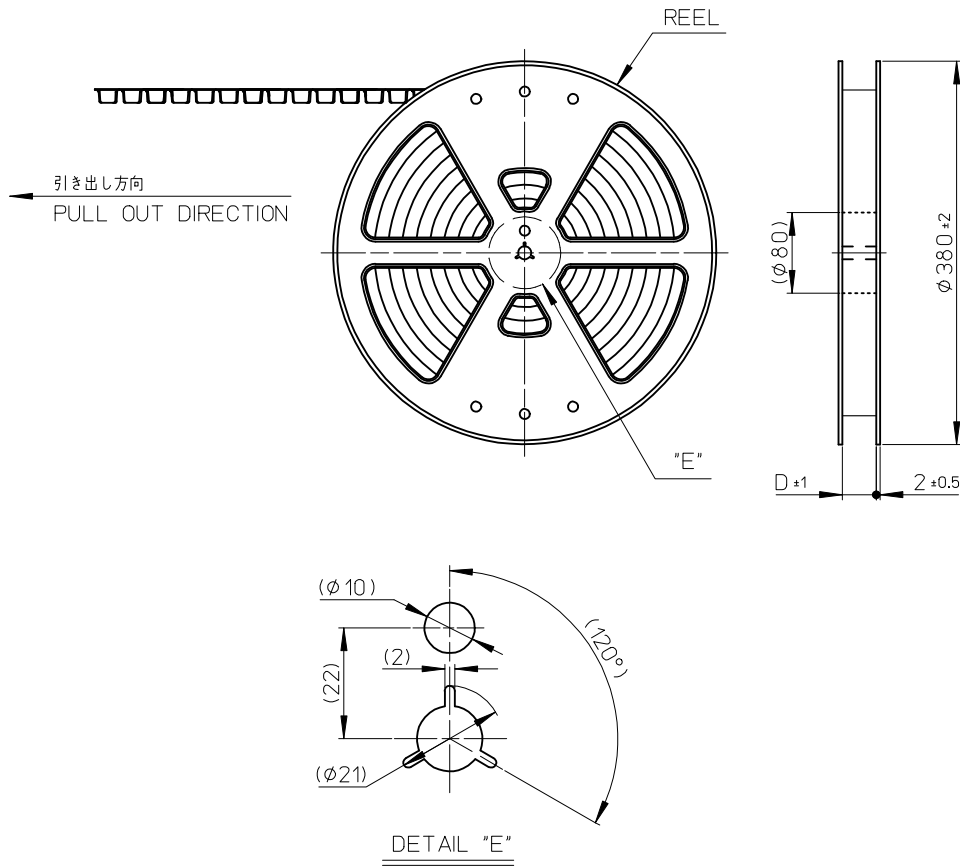
番号 NO.	部品 PART	材質 MATERIAL
①	ウエハー WAFER	耐熱ナイロン、UL94V-0、色: シート2参照 HEAT RESISTANCE NYLON, UL94V-0, COLOR:SEE SHEET2
②	ソルダピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 金メッキ : 0.1 MICRO METER MINIMUM. GOLD PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING
③	ネイル NAIL	黄銅 BRASS すずメッキ : 1 MICRO METER MINIMUM. TIN PLATING ニッケル下地メッキ : 1 MICRO METER MINIMUM. NICKEL UNDER PLATING

REVISED EC NO.: J2013-1460 DRYNAKAWASHIO 2013/06/10 CHKDKASAKAWA 2013/06/12 APPR:NUKITA 2013/06/12	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
		10 UNDER	±0.2	DRAWN BY TRSUZUKI	DATE 2005/02/14	TITLE 1.0 WIRE TO BOARD CONN. 2-ROW R/A WAFER ASSY -LEAD FREE-		
		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/02/14			
		30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/02/14			
		ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-501571-001	SHEET NO. 1 OF 2	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

9 8 7 6 5 4 3 2

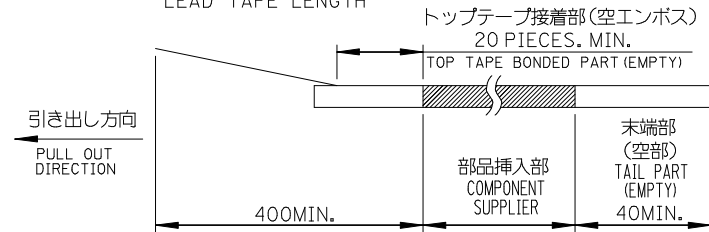
緑 GREEN		青 BLUE		赤 RED		黒 BLACK		自然色 NATURAL		色 COLOR
//		//		//		//		501571-5007		50
501571-4056	501571-**76	501571-4054	501571-**74	501571-4052	501571-**72	501571-4051	501571-**71	501571-4007	501571-**09	40
501571-3056		501571-3054		501571-3052		501571-3051		501571-3007		30
501571-2056		501571-2054		501571-2052		501571-2051		501571-2007		20
EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	EMBOSSED PACKAGE オーダー番号 ORDER NO.	CONNECTOR SERIES	CKT.

SEE SHEET 1 EC NO: J2013-1460 DRWN: KAWASHIO 2013/06/10 CHKD: KASAKAWA 2013/06/12 APPR: NUKITA 2013/06/12	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 5:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY TRSUZUKI	DATE 2005/02/14	TITLE 1.0 WIRE TO BOARD CONN. 2-ROW R/A WAFER ASSY -LEAD FREE-			
		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/02/14				
		30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/02/14				
		ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-501571-001	SHEET NO. 2 OF 2
				SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			

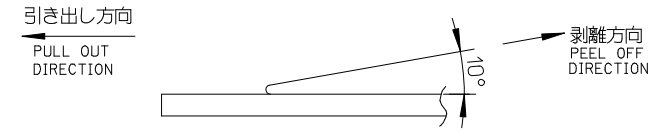


NOTES

- 製品詳細寸法については SD-501571-001 を参照ください。
RE DETAILED DIMENSION, SEE SD-501571-001
- 梱包数量： 800 個/リール
NUMBER OF CONNECTORS : 800 PIECES/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- トップテープの剥離強度：0.1~1.3N(10.2 ~ 132.5gf) (剥離方向は下図参照)
PEELING OFF FORCE OF TOP TAPE
(PEELING DIRECTION AS SHOWN IN FOLLOWING FIGURE)
尚、本規格値は、出荷時に適用。(但し、輸送時に剥離が発生しないこと)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT.
PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTION.



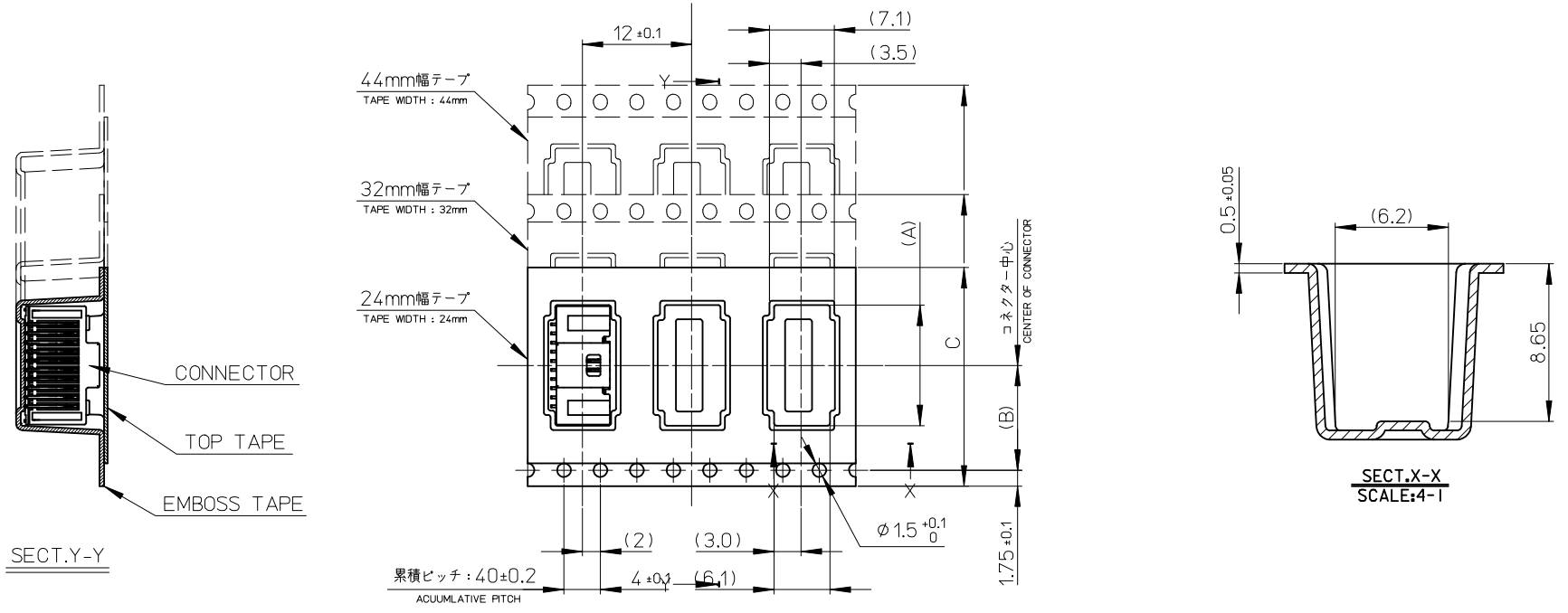
- 材料
MATERIAL
キャリアテープ：ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ：PET, PE, REF
TOP TAPE
リール：ポリスチレン (リサイクル材を含む)
REEL : POLYSTYRENE <RECYCLE MATERIAL CONTAINED>

- 乾燥剤入り防湿梱包仕様になります。(501571-**07以外)
INCLUDING DESICCANT TAPING PACKAGE.
(BESIDES 501571-**07)

- ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT.

REVISED EC NO: J2013-1460 DRWN:KASHIO 2013/06/12 CHKD:KASAKAWA 2013/06/12 APPR:NIKI ITA 2013/06/12	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED)	10 UNDER ±0.2		DRAWN BY TRSUZUKI	DATE 2005/02/14	TITLE 1.0 WIRE TO BOARD CONN. 2-ROW R/A WAFER ASSY EMBTP PKG -LEAD FREE-
		10 OVER 30 UNDER ±0.25				
		30 OVER ±0.3		CHECKED BY MYAGI	DATE 2005/02/14	
		ANGULAR ±3 °		APPROVED BY ANODA	DATE 2005/02/14	
REV C	DESCRIPTION DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 2		DOCUMENT NO. SD-501571-002		SHEET NO. 1 OF 3
		SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

引き出し方向
PULL OUT DIRECTION




45.5	44±0.3	20.2	28.3	501571-5009	501571-5007	50
			23.3	501571-4009	501571-4007	40
33.5	32±0.3	14.2	18.3	501571-3009	501571-3007	30
				501571-307*	501571-305*	
25.5	24±0.3	11.5	13.3	501571-2009	501571-2007	20
				501571-207*	501571-205*	
D	C	(B)	(A)	CONNECTOR SERIES NO.	EMBOSSED PACKAGE ORDER NO.	CKTS.

SEE SHEET 1 EC NO.: J2013-1460 DRWN: KWASHIO 2013/06/12 CHKD: KASAKAWA 2013/06/12 APPR: NUKITA 2013/06/12	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY TRSUZUKI	DATE 2005/02/14	TITLE 1.0 WIRE TO BOARD CONN. 2-ROW R/A WAFER ASSY EMBTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/02/14			
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/02/14			
ANGULAR	±3 °	MATERIAL NO. SEE CHART		DOCUMENT NO. SD-501571-002	SHEET NO. 2 OF 3		
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				

緑 GREEN	青 BLUE	赤 RED	黒 BLACK	色 COLOR	
--/--	--/--	--/--	--/--	50	501571-**7*
501571-4056	501571-4054	501571-4052	501571-4051	40	
501571-3056	501571-3054	501571-3052	501571-3051	30	
501571-2056	501571-2054	501571-2052	501571-2051	20	
EMBOSSED PACKAGE オーダー番号 ORDER NO.				CKT.	CONNECTOR SERIES NO.

自然色 NATURAL	色 COLOR	
501571-5007	50	501571-**09
501571-4007	40	
501571-3007	30	
501571-2007	20	
EMBOSSED PACKAGE オーダー番号 ORDER NO.	CKT.	CONNECTOR SERIES NO.

SEE SHEET 1 EC NO: J2013-1460 DRW:KAWASHIO 2013/06/12 CHK:D:KASAKAWA 2013/06/12 APPR:NUKITA 2013/06/12	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY TRSUZUKI	DATE 2005/02/14	TITLE 1.0 WIRE TO BOARD CONN. 2-ROW R/A WAFER ASSY EMBTP PKG -LEAD FREE-		
	10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/02/14	 DOCUMENT NO. SD-501571-002 SHEET NO. 3 OF 3		
	30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/02/14			
	ANGULAR ±3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE CHART	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			